



Material Content Data Sheet



Sales Product Name				IGB20N65S5		Issued		20. July 2018	
MA#				MA001581436					
Package				PG-TO263-3-2		Weight*		1556.85 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.245	0.08	0.08	800	800	
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	iron	7439-89-6	0.304	0.02		196		
	non noble metal	copper	7440-50-8	304.026	19.53	19.56	195282	195537	
	non noble metal	aluminium	7429-90-5	2.725	0.18	0.18	1750	1750	
wire	non noble metal	aluminium	7429-90-5	2.725	0.18	0.18	1750	1750	
encapsulation	organic material	carbon black	1333-86-4	10.330	0.66		6635		
	plastics	epoxy resin	-	113.629	7.30		72986		
	inorganic material	silicondioxide	60676-86-0	564.699	36.27	44.23	362718	442339	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6203	6203	
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	147	148	
solder	non noble metal	tin	7440-31-5	0.031	0.00		20		
	noble metal	silver	7440-22-4	0.038	0.00		25		
	non noble metal	lead	7439-92-1	1.467	0.09	0.09	942	987	
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		106		
	non noble metal	iron	7439-89-6	0.548	0.04		352		
	non noble metal	copper	7440-50-8	547.666	35.18	35.23	351778	352236	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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